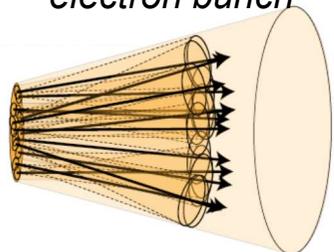


# The Data & Infrastructure Density Challenge in Ultra High Speed Imagers - with CoRDIA as example -

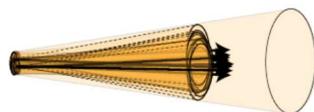
Ulrich Trunk | DESY FS-DS | 17.03.2022

## PETRA-IV: Upgrade to a diffraction limited ring (2028)

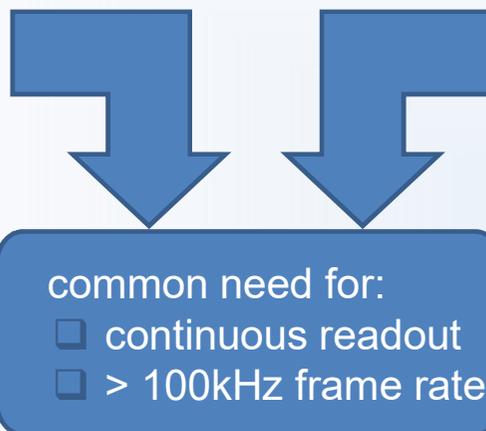
PETRA-III  
electron bunch



PETRA-IV  
electron bunch

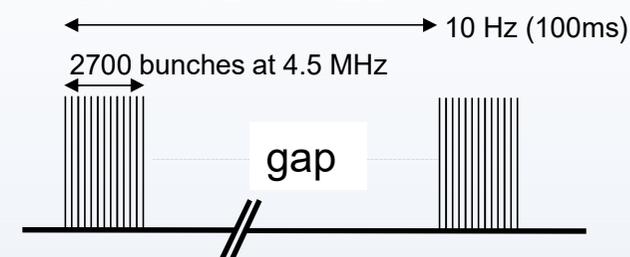


- 100-1000 fold improvement in brilliance and coherent flux
- Frame rate requirements in some experiments increase from kHz to **>100 kHz** (**continuous**) readout

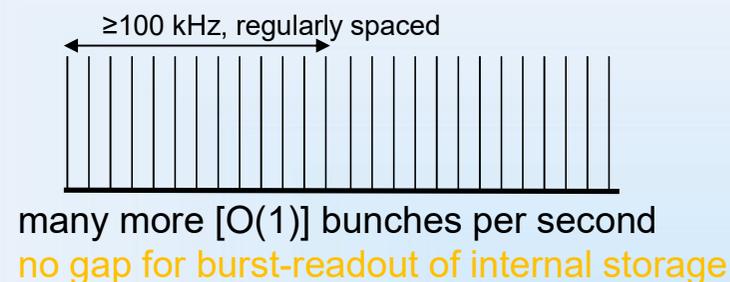


## European XFEL: CW mode operation (20??)

Current Eu.XFEL



CW operation

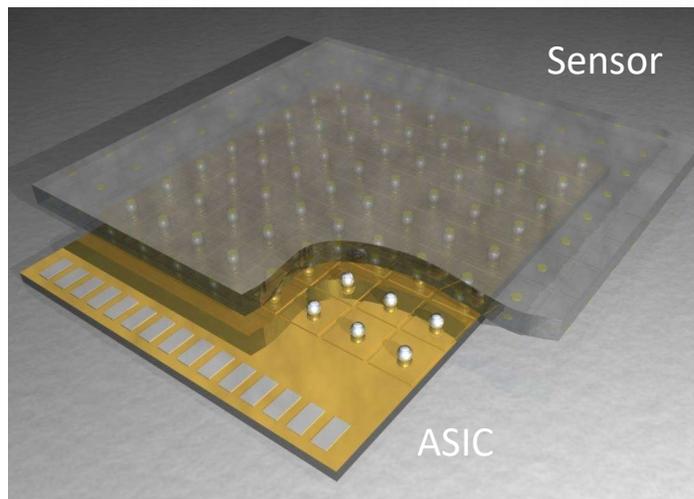


# CoRDIA – Continuous Readout Digitising Imager Array



## CoRDIA – Continuous Readout Digitising Imager Array - is...

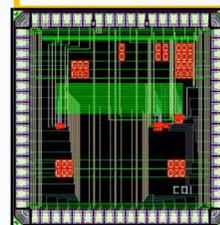
- ❑ Targeted to DL Synchrotron sources (like PETRA IV)
- ❑ CW FELs (future CW Mode of European XFEL)
- ❑ Collaboration of Bonn University & DESY



17 March 2022

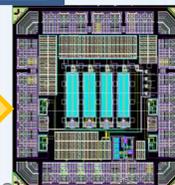
## CoRDIA is...

- ❑ A Hybrid Pixel Detector
- ❑ Charge Integrating
- ❑ Pixel size  $100\mu\text{m} \times 100\mu\text{m}$
- ❑ Continuous Frame Rate  $f_{FR} \approx 150\text{kHz}$  ( $\geq 100\text{kHz}$ )
- ❑ On-Chip Digitisation @  $\geq 10$  bit
- ❑ GWT Data Transmission (based on Timepix4 Implementation)
- ❑ Dynamic Gain Switching (à la AGIPD)  
-> +2 bit

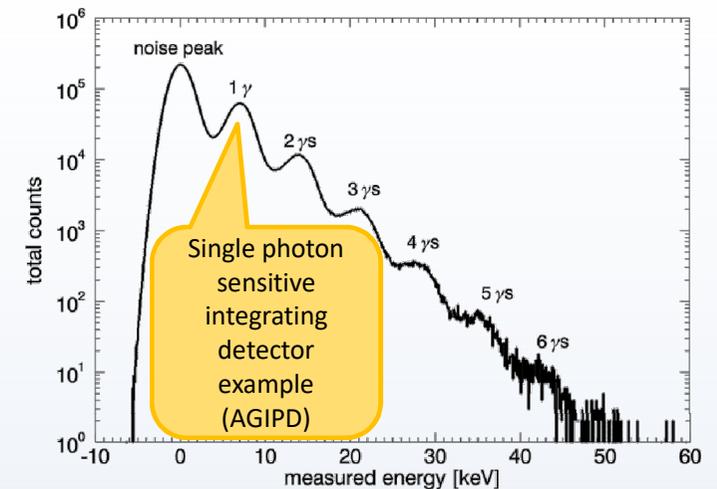


CoRDIA 0.1 (analogue) &

SAR ADC test chips

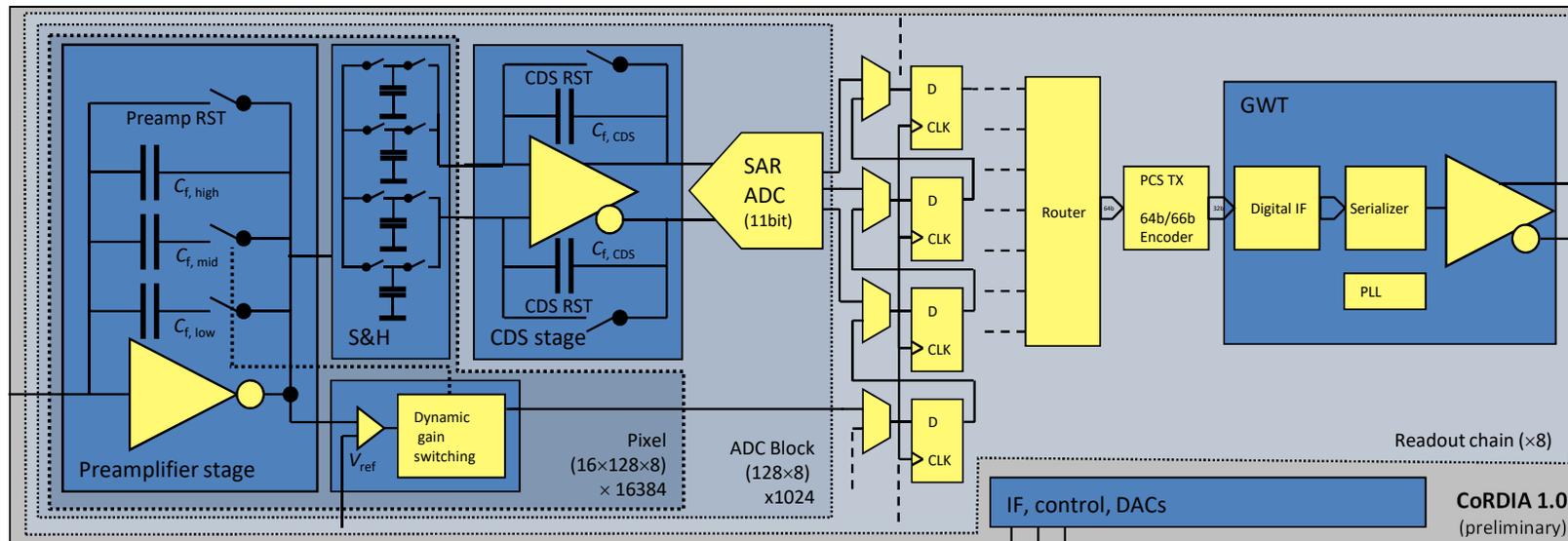


Ulrich Trunk, DESY FS-DS



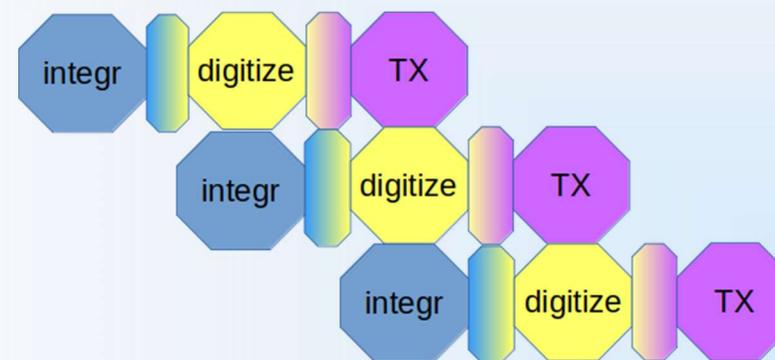
- ❑ Single-Photon Sensitive (@  $\leq 12\text{keV}$ )
- ❑  $\geq 10\text{k}$  Photon Dynamic Range
- ❑ Dead-Time free Pipelined Operation
- ❑ Targeted at Electron-Collecting Sensors:
  - ❑ Si for hard (12keV X-Rays)
  - ❑ High-Z materials for  $E > 15\text{keV}$
  - ❑ Active (LGAD) Sensors for low E
- ❑ Little or No Dead Area

# CoRDIA – Architecture & Signal Path



## CoRDIA Architecture

- ☐ CW
- ☐ Pipelined operation
- ☐ Small dead time due to reset of integrating preamp



# A Black Box...to be filled

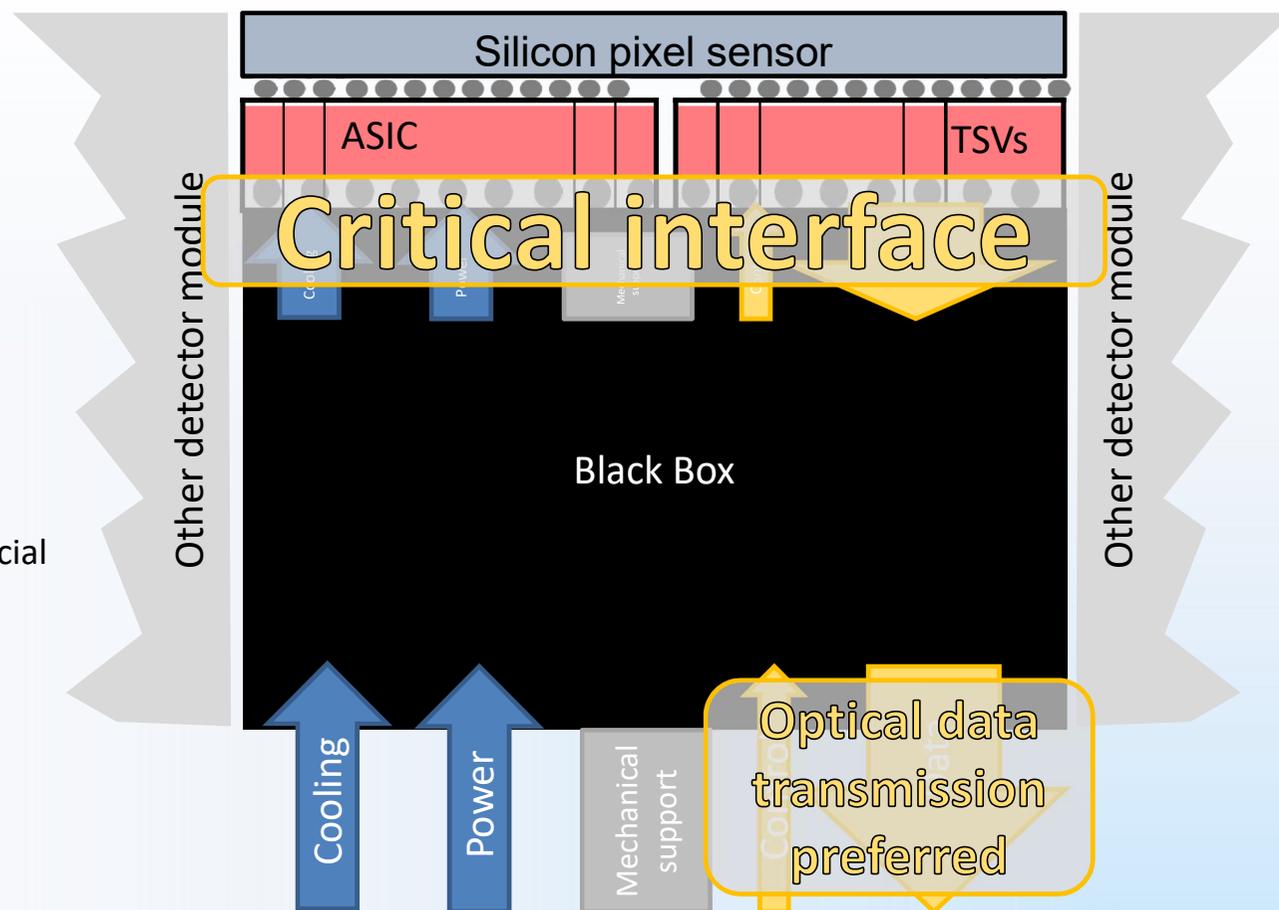
Any hybrid pixel detector needs a

- ❑ Mechanical
- ❑ Thermal
- ❑ Electrical (i.e. power supply)
- ❑ Data (i.e. control & readout)

Interface to the outside world.

Some boundary conditions:

- ❑ The interface is never completely “dumb” or passive. Intelligence may range from
  - ❑ Power supply control to
  - ❑ Data reformatting to
  - ❑ Calibration
- ❑ Electrical and optical components should be commercial of the shelf components (COTS) to minimize development effort.
- ❑ The hybrid detector itself is a “wear part” due to radiation damage and should be easily exchangeable
- ❑ Operation in vacuum is required for single photon sensitivity
- ❑ Optical data transmission to the outside world is desirable



# A little Math..... ..... is where the Trouble starts!

## Per Pixel:

- 11 bit from ADC resolution
- 2 bit from gain encoding
  
- 13 bits/(image•pixel)
- 150 kHz frame rate
  
- 1.95 Mbit/(s•pixel)

## Per ADC Block:

- 16 pixel/ADC
  
- 31.2 Mbit/ADC block

## Per MGBT Link:

- 128 ADC blocks
- 2048 pixel
- 64b/66b encoding
  
- 3.9935 Gbit/(s•link) input
  
- 4.1184 Gbit/(s•link) output 😊

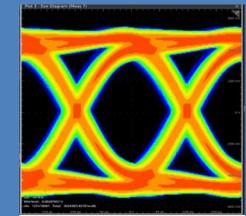
## ASIC :

- 100µm × 100µm pixel size
- 128 × 128 pixels
  
- 12.8mm × 12.8mm size
- 16384 pixels
- 8 MGBT links 😞

- Low enough to work with the Timepix4 GWT transceiver (IP block)
- Some margin to run faster than 150 kHz
- Lower requirements on PCB design

Timepix4  
GWT @5 Gbit/s

X. Llopart,  
On behalf of the Medipix4 Collaboration  
11 th February 2022  
CERN seminar



- Too many!
- 128 MGBT links for an AGIPD-sized (8×2 chip) Module
- FPGAs with SoC are all ≤96 GTH/GTY TX
- Only Xilinx VU13P has 128 GTH/GTY TX, but no SoC



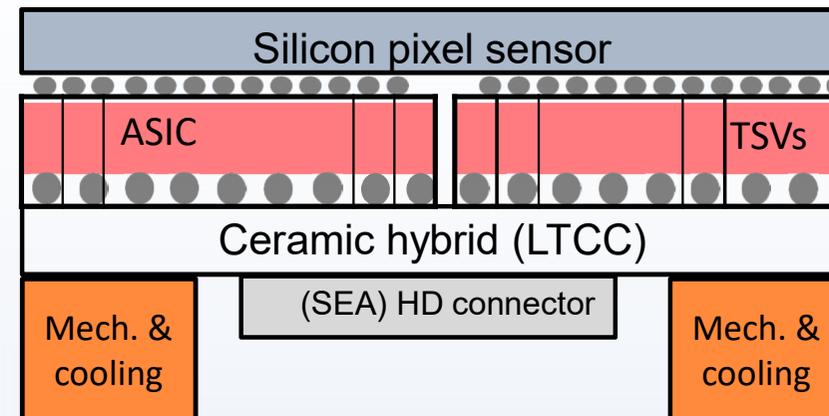
Sensor &  
8×2 chip module

Readout board  
(w. SoC FPGA)

# A few things to consider...

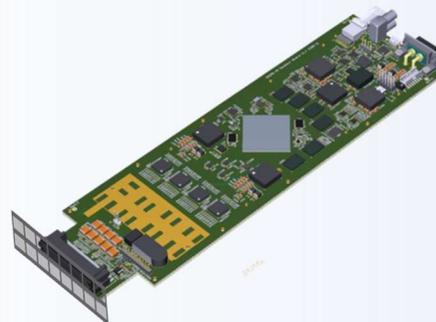
Sensors and ASICs are usually mounted on a ceramic hybrid (LTCC):

- ❑ For matching of thermal expansion coefficients
- ❑ For thermal conductance
- ❑ Design rules are difficult
  - ❑ Impedance matching and
  - ❑ Routing recommendations may not be fulfilled
- ❑ The same may hold true for the RDL on the bottom of the ASICs



Components are characterised/qualified under optimal conditions:

- ❑ Signal integrity may be compromised by
  - ❑ A sequence of connectors
  - ❑ Routing areas with sub-optimal impedance control
  - ❑ Crosstalk in congested areas



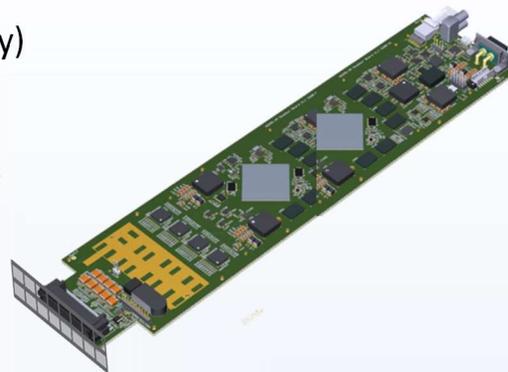
Power consumption is non-negligible

- ❑ Estimated 1.0..1.5 W/cm<sup>2</sup> (30cm<sup>2</sup>)
- ❑ Substantial area needed
  - ❑ Contact surfaces
  - ❑ Thermal vias
  - ❑ MC cooling

Masterbox

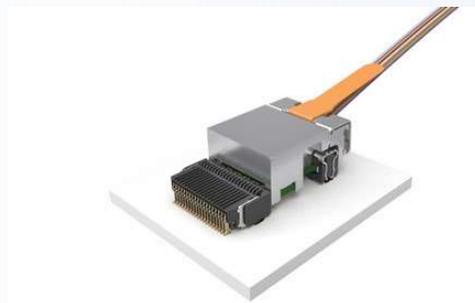
AGIPD-like FPGA based RoB not desirable:

- ❑ Operation in vacuum (Single-photon sensitivity)
- ❑ Power consumption (2 FPGAs!)
- ❑ Routing of multiple MGBT signals via (SEA) HD connector
- ❑ Signal integrity?



Ideal: Optical data transmission

- ❑ Ideally on back of FEM LTCC
- ❑ Fire Fly:
  - ❑ 12 channels
  - ❑ Footprint: 11mm × 22mm
- ❑ 2 CoRDIA 1.0 ASICS:
  - ❑ Footprint: 25.6mm × ~14mm
  - ❑ 16 channels ☺



Current solution(s):

- ❑ Bite the bullet
  - ❑ Use 2 FPGAs and
  - ❑ invest in a good cooling system
- ❑ Technology extrapolation
  - ❑ Pray for the help of ITRS roadmap and Moore's Law
  - ❑ Wait for FPGAs or optical Tx with more links
- ❑ "Dumb" RoB with optical Tx

Ideal:

- ❑ Anything that integrates data transmission better with other "infrastructures" like
  - ❑ Cooling
  - ❑ Power supplies
- ❑ 2.5D or 3D integration
- ❑ MC cooling